

SID

Factory: Rot am See

Article:

ML10

Provided:

Customer:

Date:

21.08.2025



Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	195		2	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		3	
		70	L2		
B-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		4	A01
		70	L3		
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	160		5	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		6	
		70	L4		
B-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		7	A02
		70	L5		
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	160		8	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		9	B00
		70	L6		
B-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		10	A03
		70	L7		
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	160		11	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		12	
		70	L8		
B-RAS-ML-0.10-070+070-460x305-TG150HF-...	50202542	100		13	A04
		70	L9		
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	195		14	
A-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		15	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	16	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

1866 µm

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